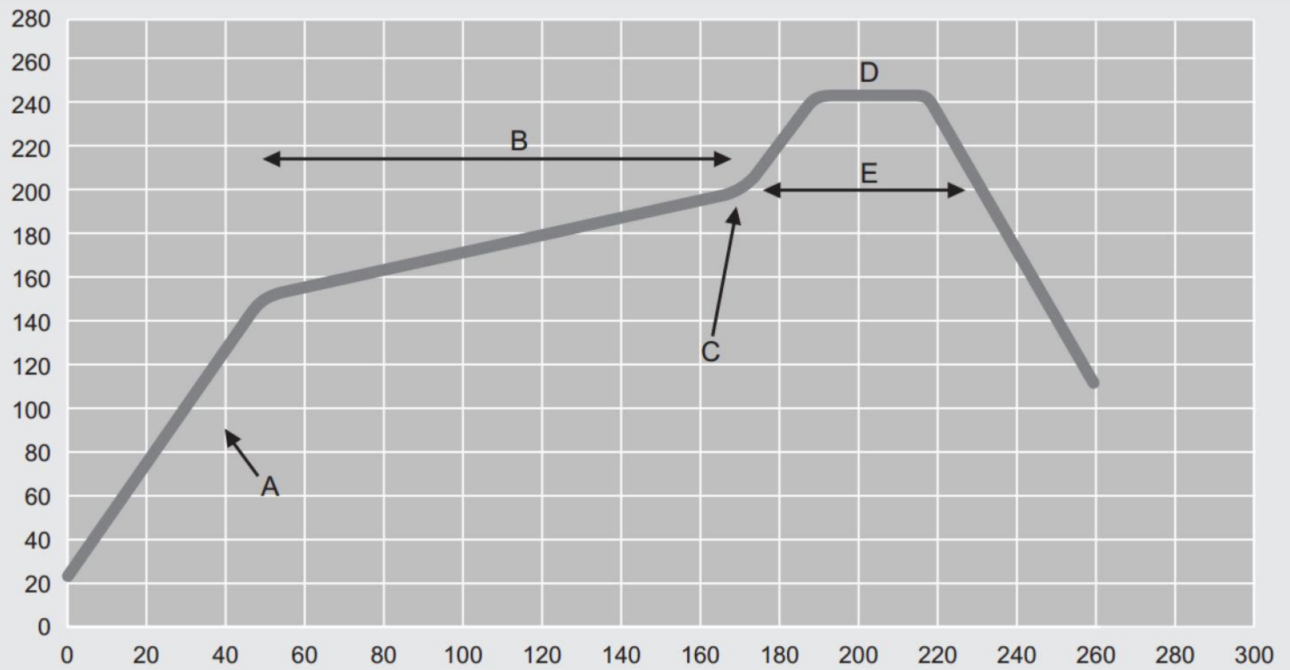

Precautions

1. Preheat

* Set the temperature rising speed A at a rate of **1~3**℃/s. Careful about rapid temperature rise in preheat zone as it may cause excessive slumping of the solder paste.

* Appropriate preheat time B will be from **60** to **120** seconds. If the preheat is insufficient, rather large solder balls tend to be generated. Conversely, if performed excessively, fine balls and large balls will generate in clusters at a time.

* Appropriate preheat ending temperature C will be from **150** to **200**℃. If the temperature is too low, non-melting tends to be caused in the area with large heat capacity after reflow.

2. Heating

* Careful about sudden rise in temperature as it may worsen the slump of solder paste.

* Set the peak temperature D in the range from **240** to **250**℃

* Adjust the melting time that the time over **227**℃, could net less then **20-80**seconds.

3. Cooling

* Careful about slow cooling as it may cause the positional shift of parts and decline in joining strength at times.

* Perform adequate test in advance as the reflow temperature profile will vary according to the conditions of parts and

* boards, and the specifications of the reflow furnace.